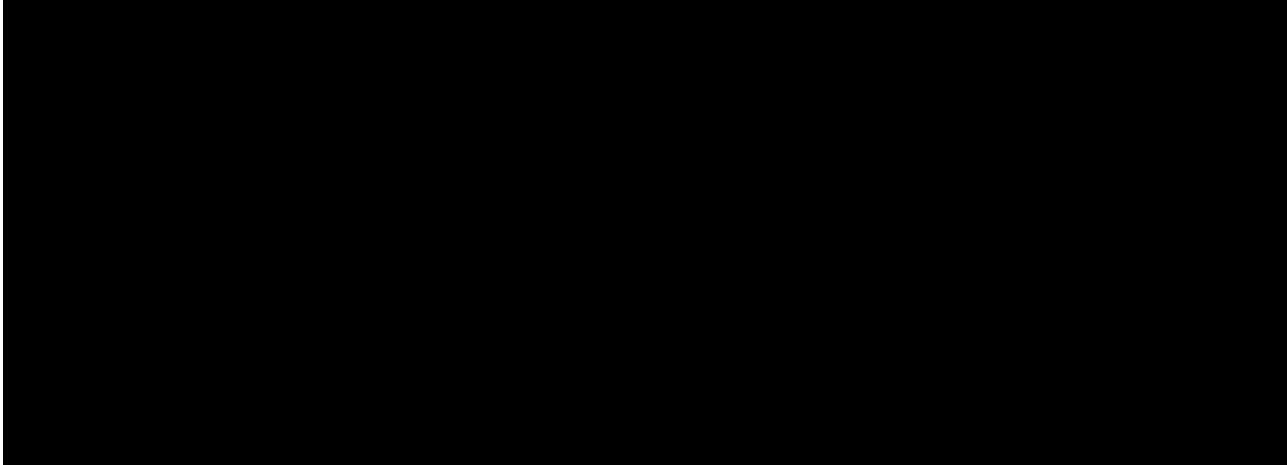


BCX56

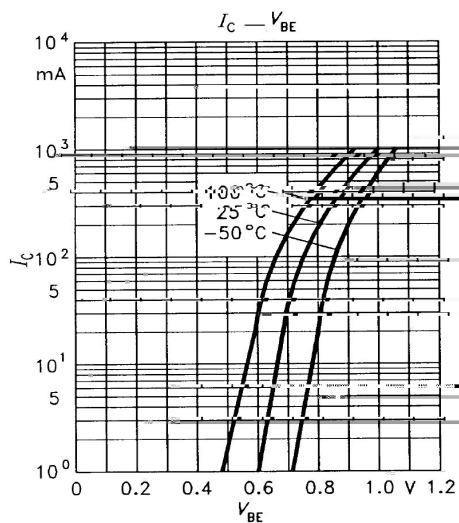
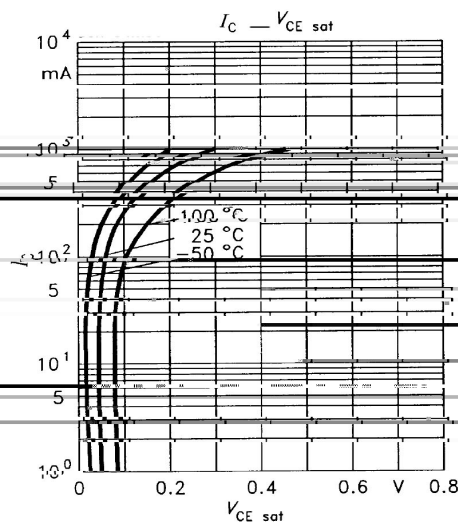
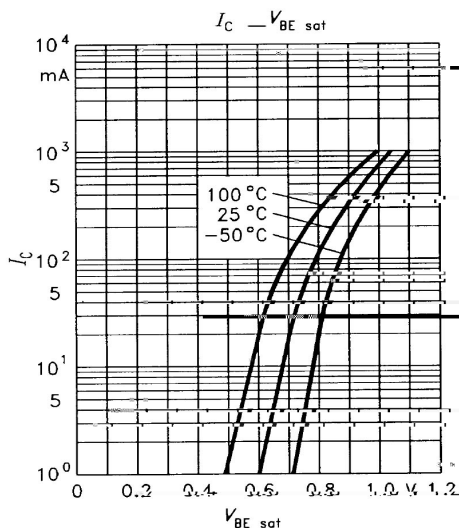
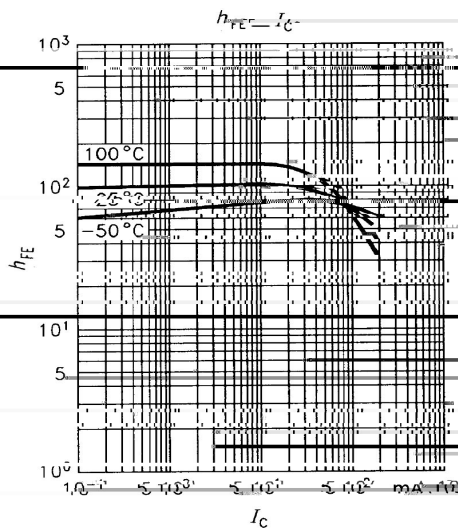
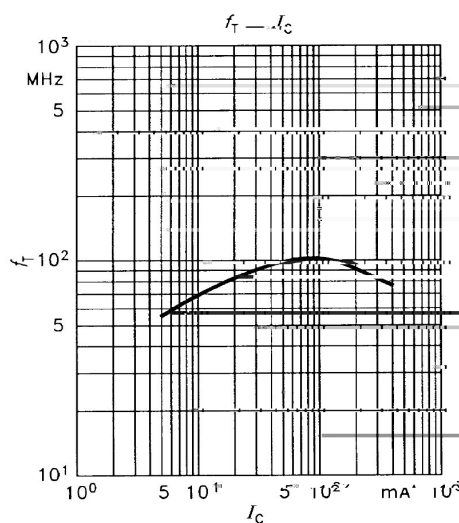


Collector to Emitter Voltage	V_{CE0}	80	V
Emitter to Base Voltage	V_{EBO}	5	V
Collector Current-Continuous	I_C	1	A
Peak Collector Current	I_{CM}	1.5	A
Peak Base Current	I_{BM}	0.2	A
Collector Power Dissipation	$P_C(T_C=25^\circ\text{C})$	1.3	W
Storage Temperature Range	T_{stg}	-55° 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=100\mu\text{A}$ $I_E=0$	100			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=500\mu\text{A}$ $I_B=0$	80			V

Emitter to Base Breakdown Voltage V

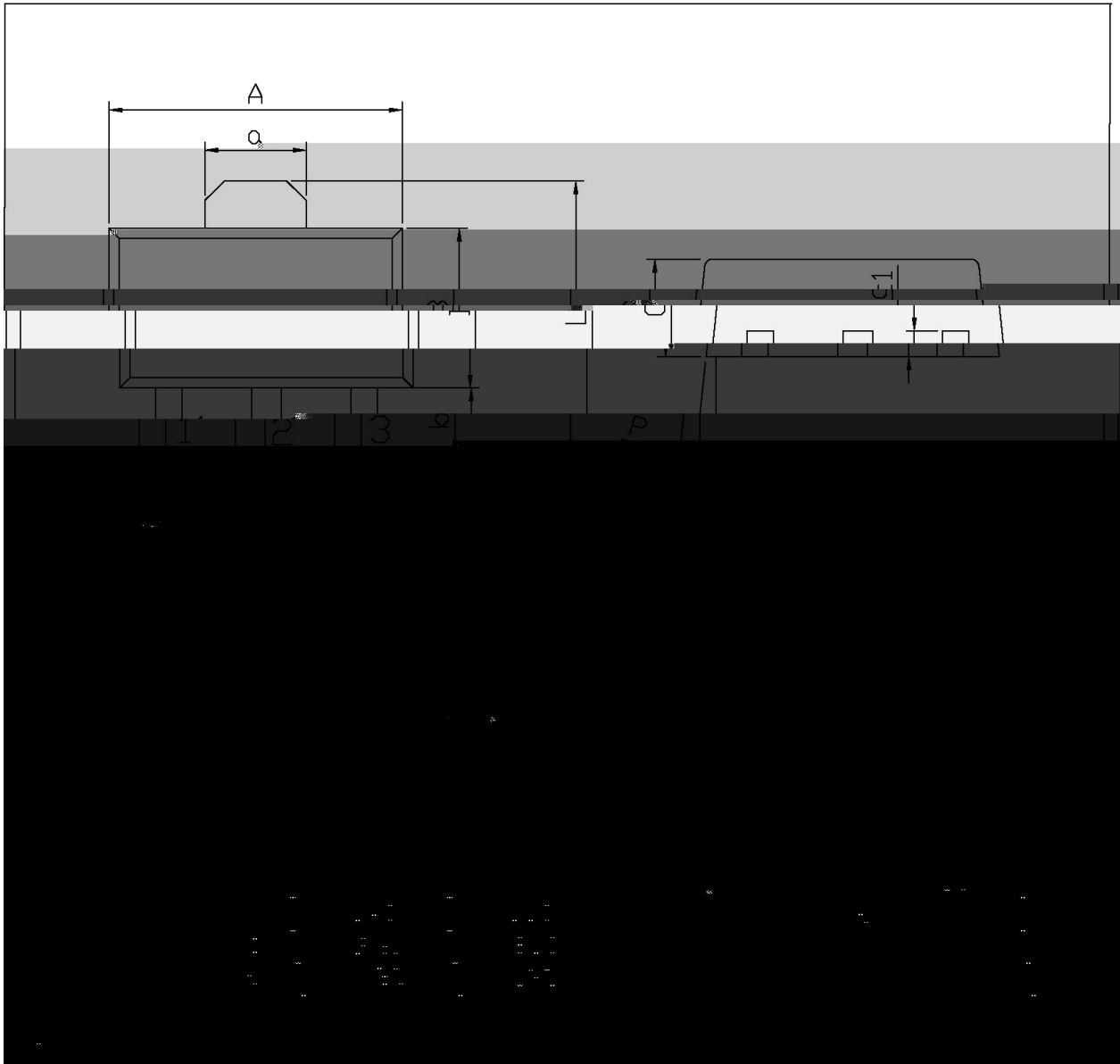
电 气 特 性 曲 线 / Electrical Characteristic Curve



⌘ É Ò Ì f / Package Dimensions

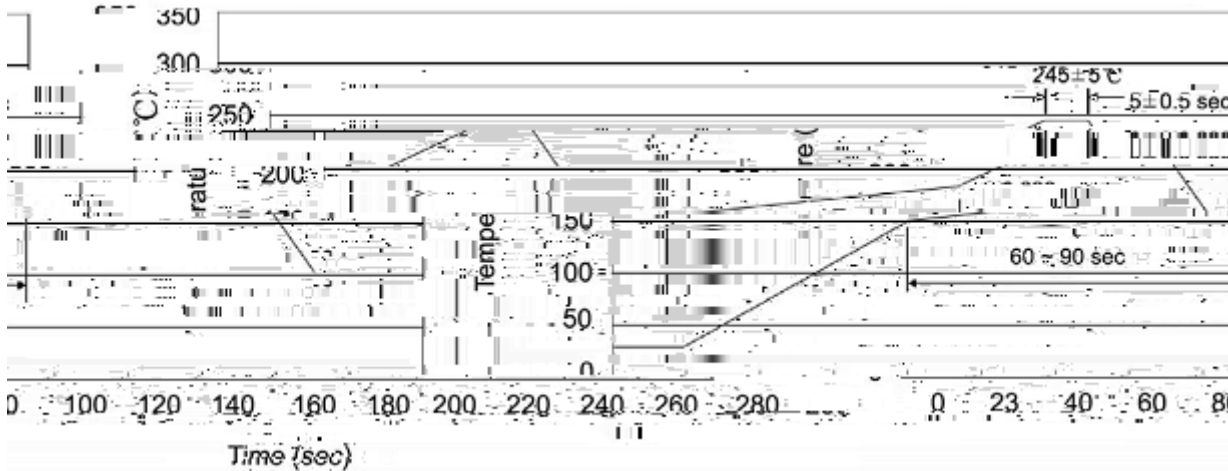
SOT-89

单位: mm



** Lot No. Code, code change with Lot No.

Whp shudwxuh Suriloh i ru LU Uhior z Vroghulqj+Se0luhh,



б " X

1. 25~150 °C, Time: 60~90sec;
2. 245±5 °C, Duration: 5±0.5sec;
3. Cooling Speed: 2~10 °C/sec.

Note:

1. Preheating: 25~150 °C, Time: 60~90sec.
2. Peak Temp.: 245±5 °C, Duration: 5±0.5sec.
3. Cooling Speed: 2~10 °C/sec.

Resistance to Soldering Heat Test Conditions

□ γ χ 260±5 °C, Time: 10±1 sec. Temp.: 260±5 Time: 10±1 sec

Packaging SPEC.

о` γ т / REEL

Package Type	Units					Dimension (unit mm ³)		
						p		

Notices